Application No. 09/523,745



AMENDMENTS TO THE SPECIFICATION

In the Specification

Please substitute the following amended paragraph(s) and/or section(s) (deleted matter is shown by strikethrough and added matter is shown by underlining):

Page 13, line 7-line 12:

Referring to FIG. 6, 15, and 16, the space between each vertically adjacent pair of wafer guides and the distance across the interior of the carrier defines a wafer insertion and removal level and a wafer slot 244. Similarly, an the insertion and removal level 228.1 is defined by the area between vertically adjacent wafer support shelves 220.

Page 18, line 1 to line 4:

Referring to FIG. 24, a cross section through the H-bar wafer carrier taken at line 24-24 of FIG. 24D-23D is shown and illustrates the engagement of the wafer 290 with the wafer guide 310.

RECEIVED
MAR 0 5 2004

TECHNOLOGY CENTER R3700